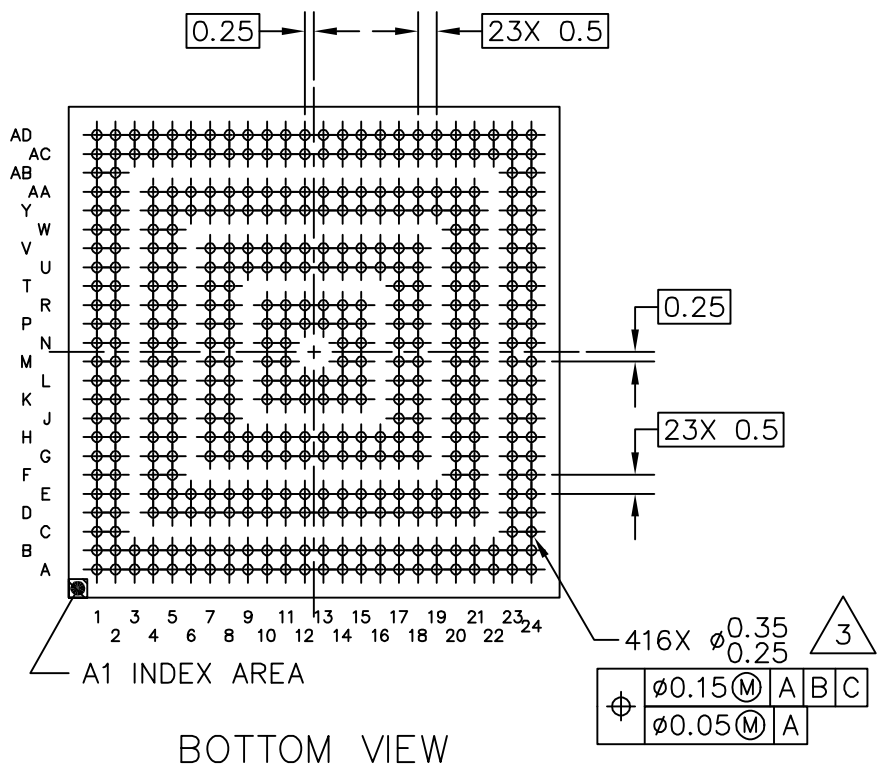
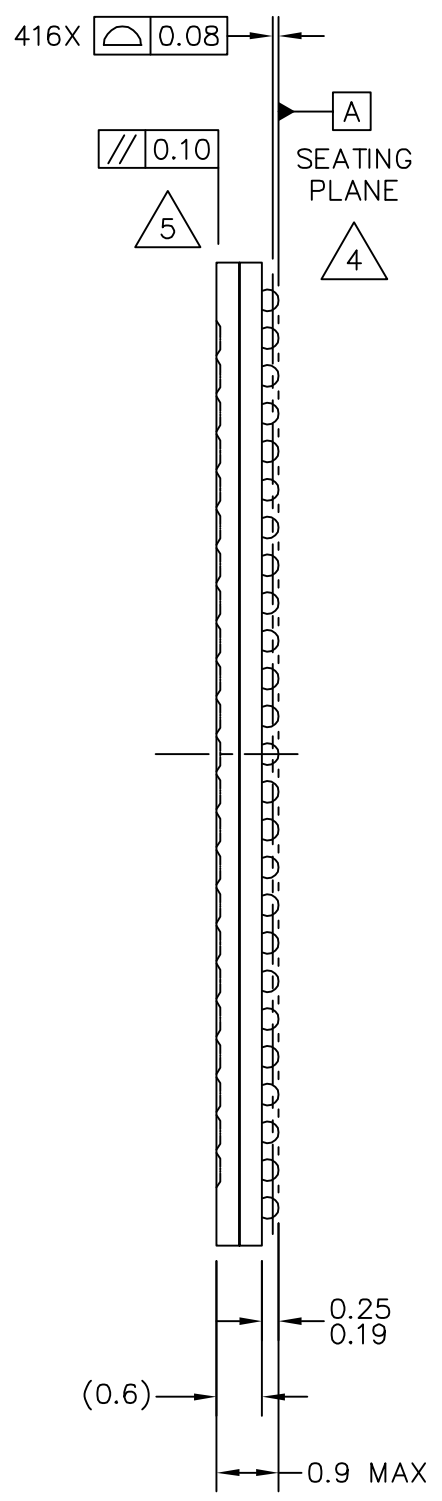


TOP VIEW



BOTTOM VIEW



SIDE VIEW

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TITLE: PBGA STACKABLE, VERY THIN, FINE PITCH, 416 I/O, 13 X 13 PKG, 0.5 MM PITCH (MAP)	DOCUMENT NO: 98ASA00268D	REV: 0	
	CASE NUMBER: 2157-01	08 OCT 2010	
	STANDARD: NON-JEDEC		



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK AND LANDING PADS ON TOP SURFACE OF PACKAGE.

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